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ON Semiconductor®

FDP027N08B

N-Channel PowerTrench[®] MOSFET 80 V, 223 A, 2.7 m Ω

Features

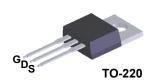
- $R_{DS(on)}$ = 2.21 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 100 A
- Low FOM $R_{DS(on)} \cdot Q_G$
- Low Reverse-Recovery Charge, Q_{rr} = 112 nC
- · Soft Reverse-Recovery Body Diode
- · Enables High Efficiency in Synchronous Rectification
- · Fast Switching Speed
- · 100% UIL Tested
- This device is Pb-Free, Halogen Free/BFR Free and is RoHS Compliant

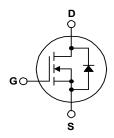
Description

This N-Channel MOSFET is produced using ON Semiconductor's PowerTrench[®] process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- · Battery Protection Circuit
- · Motor Drives and Uninterruptible Power Supplies





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter	FDP027N08B_F102	Unit	
V _{DSS}	Drain to Source Voltage	80	V		
V _{GSS}	Gate to Source Voltage		±20	V	
I _D		- Continuous (T _C = 25°C, Silicon Limited)	223*		
	Drain Current	- Continuous (T _C = 100°C, Silicon Limited)	158*	Α	
		- Continuous (T _C = 25°C, Package Limited)	120		
I _{DM}	Drain Current	- Pulsed (Note 1)	892	Α	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	917	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns	
D	Dawer Dissipation	$(T_C = 25^{\circ}C)$	246	W	
P_{D}	Power Dissipation	- Derate Above 25°C	1.64	W/°C	
T _J , T _{STG}	Operating and Storage Temperatu	-55 to +175	°C		
T _L	Maximum Lead Temperature for S	Soldering, 1/8" from Case for 5 Seconds	300	οС	

^{*}Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 120 A.

Thermal Characteristics

Symbol	Parameter	FDP027N08B_F102	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.61	°C/W
$R_{\theta,JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDP027N08B-F102	FDP027N08B	TO-220	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{V}$	80	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	-	0.05	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 64 V, V _{GS} = 0 V	-	-	1	
		$V_{DS} = 64 \text{ V}, T_{C} = 150^{\circ}\text{C}$	-	-	500	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 100 A	-	2.21	2.7	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 100 A	-	227	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 40 V, V _{GS} = 0 V, f = 1 MHz	-	10170	13530	pF
C _{oss}	Output Capacitance		-	1670	2220	pF
C _{rss}	Reverse Transfer Capacitance		-	35	-	pF
C _{oss} (er)	Engry Related Output Capacitance	V _{DS} = 40 V, V _{GS} = 0 V	-	3025	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	137	178	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 40 \text{ V}, V_{GS} = 10 \text{ V},$	-	56	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau	I _D = 100A	-	25	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4	-	28	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	2.4	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	47	104	ns
t _r	Turn-On Rise Time	$V_{DD} = 40 \text{ V}, I_{D} = 100 \text{ A},$		-	66	142	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 4.7 Ω		-	87	184	ns
t _f	Turn-Off Fall Time		(Note 4)	-	41	92	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	223*	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	892	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} =	0 V, I _{SD} = 100 A	-	-	1.3	V
t _{rr}	Reverse Recovery Time V _{GS} =	0 V, V _{DD} = 40 V, I _{SD} = 100 A,	-	80	-	ns
Q _{rr}	Reverse Recovery Charge dI _F /dt	= 100 A/μs	-	112	-	nC

Notes:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 3 mH, I_{AS} = 24.72 A, R_G = 25 Ω , starting T_J = 25°C.
- 3. I_{SD} \leq 100 A, di/dt \leq 200 A/µs, V_DD \leq BV_DSS, starting T_J = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

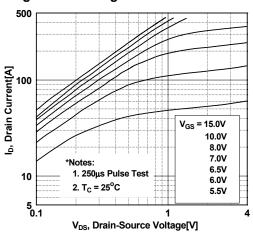


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

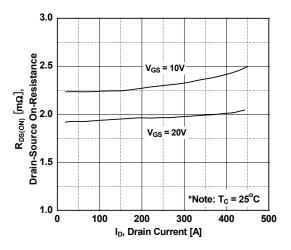


Figure 5. Capacitance Characteristics

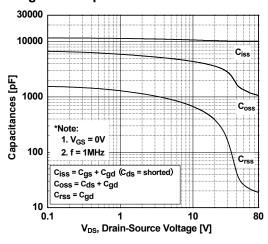


Figure 2. Transfer Characteristics

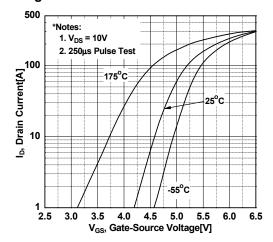


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

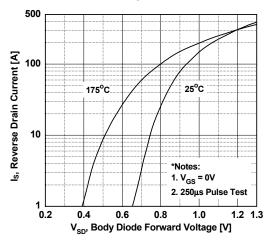
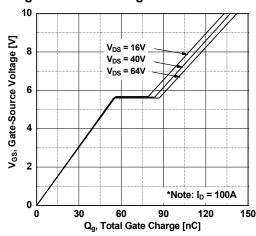


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

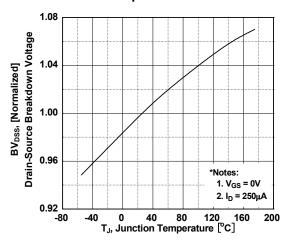


Figure 9. Maximum Safe Operating Area

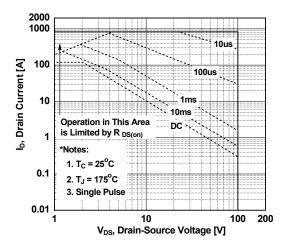


Figure 11. Eoss vs. Drain to Source Voltage

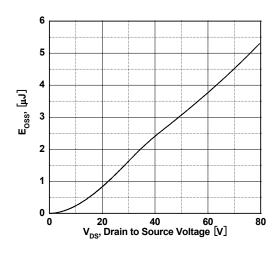


Figure 8. On-Resistance Variation vs. Temperature

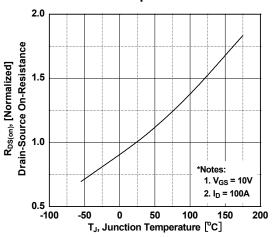


Figure 10. Maximum Drain Current vs. Case Temperature

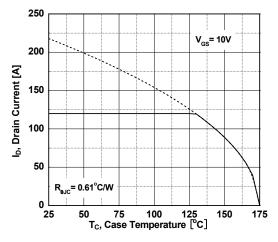
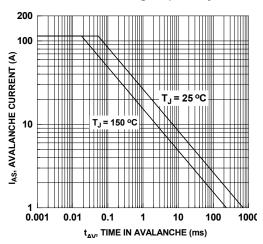
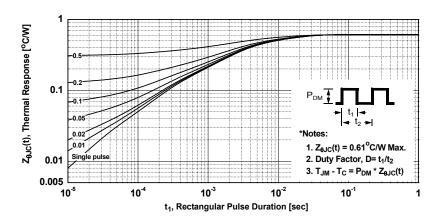


Figure 12. Unclamped Inductive Switching Capability



Typical Performance Characteristics (Continued)

Figure 13. Transient Thermal Response Curve



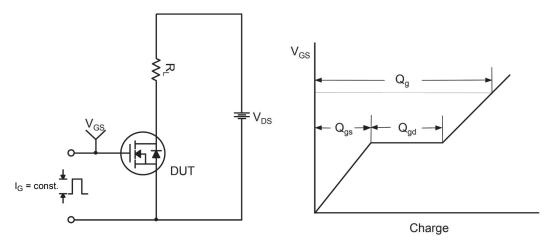


Figure 14. Gate Charge Test Circuit & Waveform

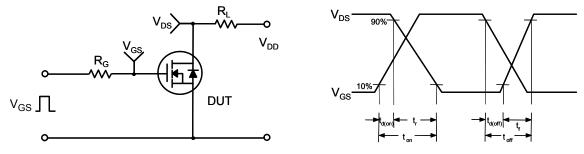


Figure 15. Resistive Switching Test Circuit & Waveforms

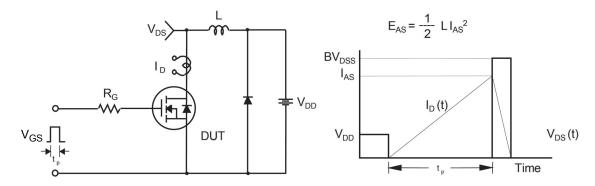
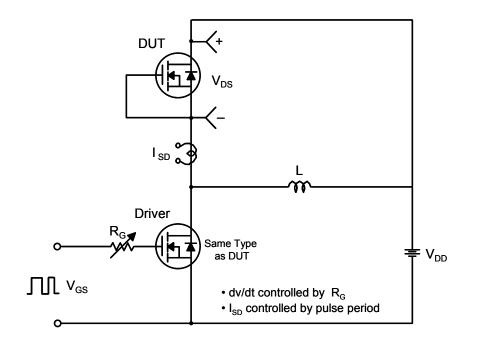


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms



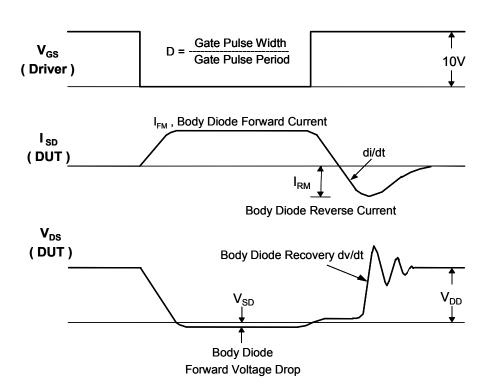
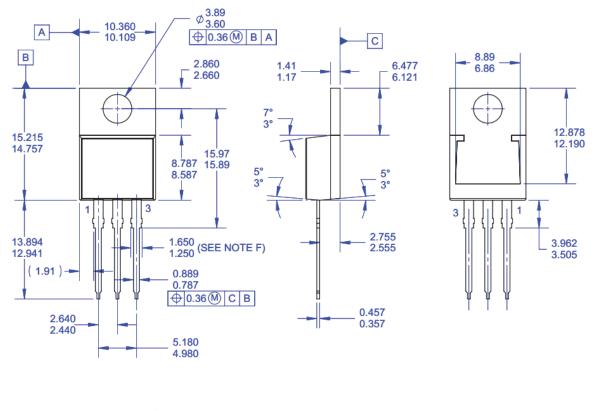


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



5° 4.672 4.472

NOTES:

- A. PACKAGE REFERENCE: JEDEC TO220 **VARIATION AB**
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS,
- MOLD FLASH AND TIE BAR PROTRUSIONS.
 THIS PACKAGE IS FSZZ INTERNAL PRODUCTION
- AND INTENDED FOR DELTA CUSTOMER ONLY.
- F. MAX WIDTH FOR F102 DEVICE = 1.35mm. G. DRAWING FILE NAME: T0220T03REV3

Figure 18. TO-220, Molded, 3-Lead, Jedec Variation AB (Delta)

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